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ABSTRACT

The present invention discloses a thermosetting resin composition which comprises (A) 35 to 75 parts by weight of
5 a thermosetting resin comprising a compound having a dihydrobenzoxazine ring as a main component, (B) 10 to 25 parts by weight of a polycondensation product of a phenol, a compound having a triazine ring and an aldehyde, and (C) 10 to 45 parts by weight of an epoxy resin, based on 100
10 parts by weight of the total amount of organic solid components of Components (A), (B) and (C), and (i) a bisphenol F epoxy resin having a weight average molecular weight of 1,000 to 3,000, or (ii) a mixed epoxy resin of
bisphenol F epoxy resin and bisphenol A epoxy resin having
15 a weight average molecular weight of 1,000 to 3,000, is contained in Component (C) in an amount of 0 to 100% by weight of Component (C); and a prepreg, a laminated board for a wiring board and a wiring board using the same.